

221.70 mm* 85.28 mm*5.35 mm

MWON Notebook Thermal Module with 1
Copper Heat Pipes & Copper FINs & Copper Back
Plate

Technical Specifications

Part No.	1C100000200
Product Name	MWON Notebook Thermal Module with 1 Copper Heat Pipes & Copper FINs & Copper Back Plate
Trademark	MWON
Product Size	221.70 mm* 85.28 mm*5.35 mm
FIN Material	CU1100
Heat Pipe Material	CU1020
Back Plate Material	CU1100
Color	Natural
Environmental protection	All raw materials shall comply with RoHS2.0, REACH, HF & etc.
Packing Method	Plastic tray, carton, pallet

Others

MOQ	1000 pcs
Delivery Lead Time	3-4 weeks
Production Capacity	100000 pcs/Year
HS Code	8414599050
Place Of Origin	Dongguan, Guangdong, China